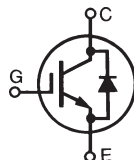




# THE DATASHEET OF IXBT2N250



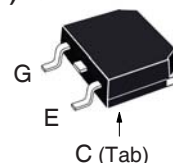
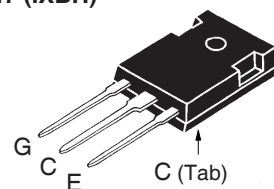
**High Voltage, High Gain  
BIMOSFET™**
**IXBH2N250  
IXBT2N250**
**Monolithic Bipolar MOS  
Transistor**


$$V_{CES} = 2500V$$

$$I_{C110} = 2A$$

$$V_{CE(sat)} \leq 3.80V$$

Symbol	Test Conditions	Maximum Ratings	
$V_{CES}$	$T_C = 25^\circ C$ to $150^\circ C$	2500	V
$V_{CGR}$	$T_J = 25^\circ C$ to $150^\circ C$ , $R_{GE} = 1M\Omega$	2500	V
$V_{GES}$	Continuous	$\pm 20$	V
$V_{GEM}$	Transient	$\pm 30$	V
$I_{C25}$	$T_C = 25^\circ C$	5	A
$I_{C110}$	$T_C = 110^\circ C$	2	A
$I_{CM}$	$T_C = 25^\circ C$ , 1ms	13	A
<b>SSOA</b>	$V_{GE} = 15V$ , $T_{VJ} = 125^\circ C$ , $R_G = 47\Omega$	$I_{CM} = 6$	A
<b>(RBSOA)</b>	Clamped Inductive Load	$V_{CE} \leq 2000$	V
$P_C$	$T_C = 25^\circ C$	32	W
$T_J$		-55 ... +150	$^\circ C$
$T_{JM}$		150	$^\circ C$
$T_{stg}$		-55 ... +150	$^\circ C$
$T_L$	Maximum Lead Temperature for Soldering	300	$^\circ C$
$T_{SOLD}$	1.6 mm (0.062in.) from Case for 10s	260	$^\circ C$
$M_d$	Mounting Torque (TO-247)	1.13 / 10	Nm/lb.in
<b>Weight</b>	TO-247	6	g
	TO-268	4	g

**TO-268 (IXBT)**

**TO-247 (IXBH)**


G = Gate      D = Drain  
S = Source    Tab = Drain

G = Gate      C = Collector  
E = Emitter    Tab = Collector

**Features**

- High Blocking Voltage
- Integrated Anti-parallel Diode
- International Standard Packages
- Low Conduction Losses

**Advantages**

- Low Gate Drive Requirement
- High Power Density

**Applications**

- Switched-Mode and Resonant-Mode Power Supplies
- Uninterruptible Power Supplies (UPS)
- Laser Generator
- Capacitor Discharge Circuit
- AC Switches

Symbol	Test Conditions ( $T_J = 25^\circ C$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{CES}$	$I_C = 250\mu A$ , $V_{CE} = V_{GE}$	2500		V
$V_{GE(th)}$	$I_C = 250\mu A$ , $V_{CE} = V_{GE}$	3.0		5.5 V
$I_{CES}$	$V_{CE} = 0.8 \cdot V_{CES}$ , $V_{GE} = 0V$ $T_J = 125^\circ C$			10 $\mu A$ 100 $\mu A$
$I_{GES}$	$V_{CE} = 0V$ , $V_{GE} = \pm 20V$			$\pm 100$ nA
$V_{CE(sat)}$	$I_C = 2A$ , $V_{GE} = 15V$ , Note 1 $T_J = 125^\circ C$	3.15		V
		4.08		V

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$I_C = 2\text{A}, V_{CE} = 10\text{V}$ , Note 1	0.85	1.40	S
$C_{ies}$	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$		145	pF
$C_{oes}$			8.7	pF
$C_{res}$			3.2	pF
$Q_g$	$I_C = 2\text{A}, V_{GE} = 15\text{V}, V_{CE} = 1\text{kV}$		10.6	nC
$Q_{ge}$			0.8	nC
$Q_{gc}$			6.2	nC
$t_{d(on)}$	<b>Resistive Switching times, <math>T_J = 25^\circ\text{C}</math></b> $I_C = 2\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 2\text{kV}, R_G = 47\Omega$		30	ns
$t_r$			180	ns
$t_{d(off)}$			70	ns
$t_f$			182	ns
$t_{d(on)}$	<b>Resistive Switching times, <math>T_J = 125^\circ\text{C}</math></b> $I_C = 2\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 2\text{kV}, R_G = 47\Omega$		30	ns
$t_r$			280	ns
$t_{d(off)}$			74	ns
$t_f$			178	ns
$R_{thJC}$			3.90	$^\circ\text{C}/\text{W}$
$R_{thCS}$		0.21		$^\circ\text{C}/\text{W}$

### Reverse Diode

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$V_F$	$I_F = 2\text{A}, V_{GE} = 0\text{V}$ , Note 1			2.4 V
$t_{rr}$	$I_F = 2\text{A}, V_{GE} = 0\text{V}, -di_f/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}, V_{GE} = 0\text{V}$		0.92	$\mu\text{s}$
$I_{RM}$			9.80	A
$Q_{RM}$			4.50	$\mu\text{C}$

Note 1. Pulse test,  $t \leq 300\mu\text{s}$ , duty cycle,  $d \leq 2\%$ .

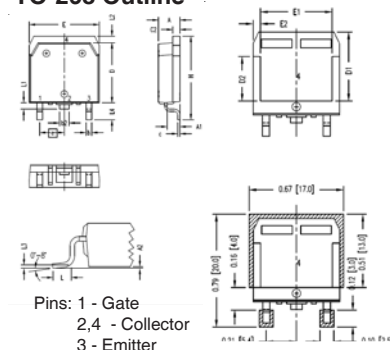
### PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS Reserves the Right to Change Limits, Test Conditions and Dimensions.

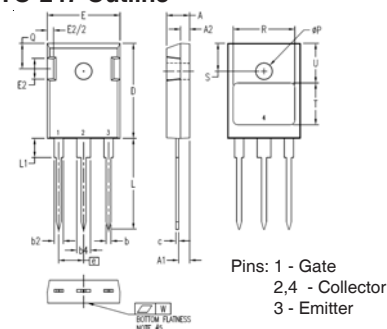
IXYS MOSFETs and IGBTs are covered 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2  
by one or more of the following U.S. patents: 4,860,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2  
4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

### TO-268 Outline



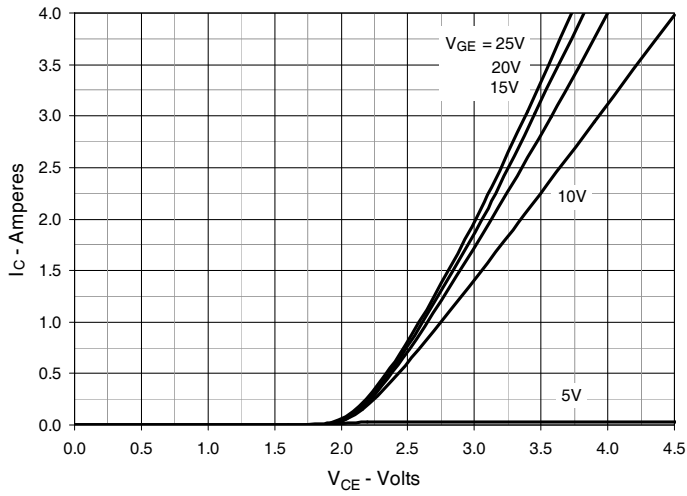
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b2	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.488	.500	12.40	12.70
D2	.320	.335	8.13	8.50
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
E2	.045	.055	1.14	1.39
e	.215	BSC	5.45	BSC
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L1	.047	.055	1.20	1.40
L2	.039	.045	1.00	1.15
L3	.010	BSC	0.25	BSC
L4	.150	.161	3.80	4.10

### TO-247 Outline

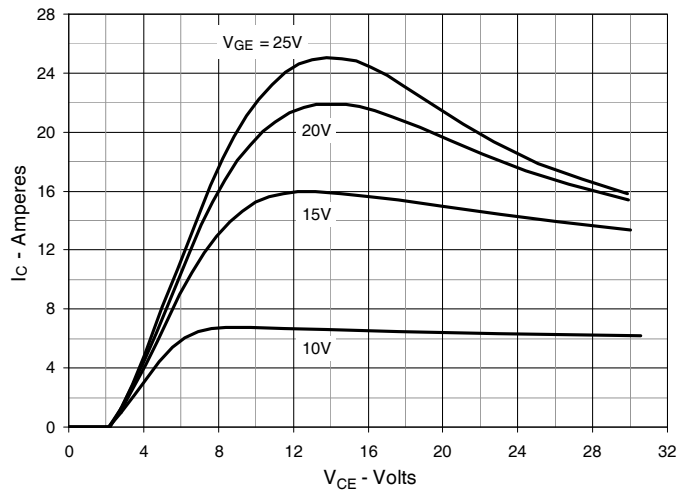


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.190	.205	4.83	5.21
A1	.087	.100	2.21	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b2	.075	.085	1.91	2.16
b4	.115	.126	2.92	3.20
c	.023	.033	0.58	0.84
D	.820	.840	20.83	21.34
E	.620	.635	15.75	16.13
E2	.175	.195	4.44	4.95
e	.215	BSC	5.45	BSC
L	.780	.810	19.81	20.57
L1	.160	.177	4.06	4.50
Q	.220	.240	5.59	6.10
R	.520	.540	13.21	13.72
S	.242	BSC	6.15	BSC
T	.355	.375	9.02	9.53
U	.345	.370	8.76	9.40
ØP	.140	.144	3.55	3.66
W	.000	.004	0.00	0.10

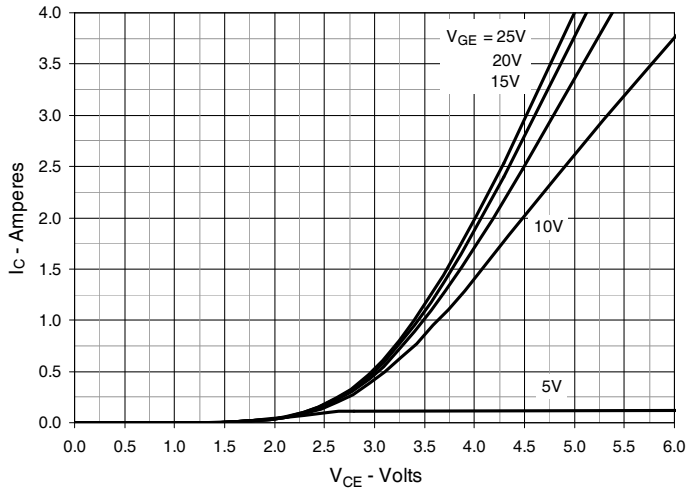
**Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$**



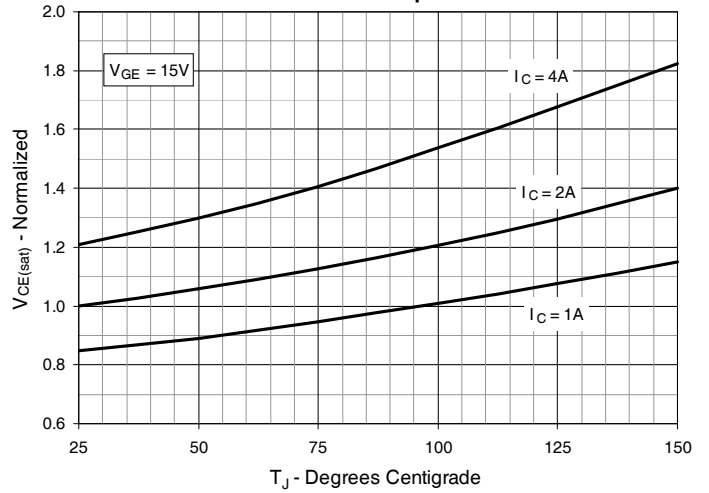
**Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$**



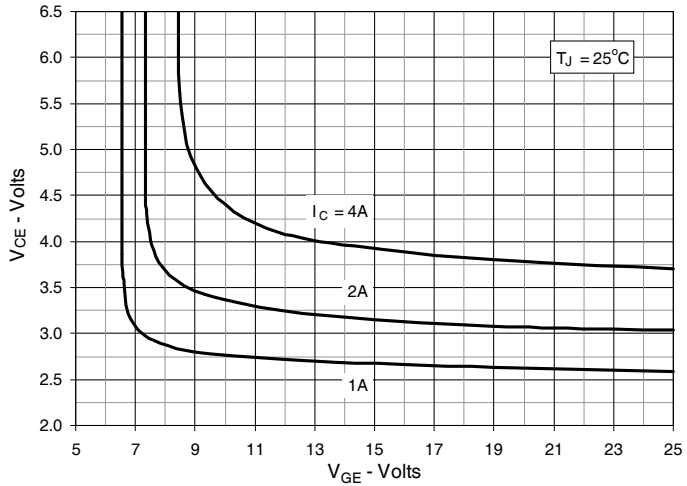
**Fig. 3. Output Characteristics @  $T_J = 125^\circ\text{C}$**



**Fig. 4. Dependence of  $V_{CE(sat)}$  on Junction Temperature**



**Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage**



**Fig. 6. Input Admittance**

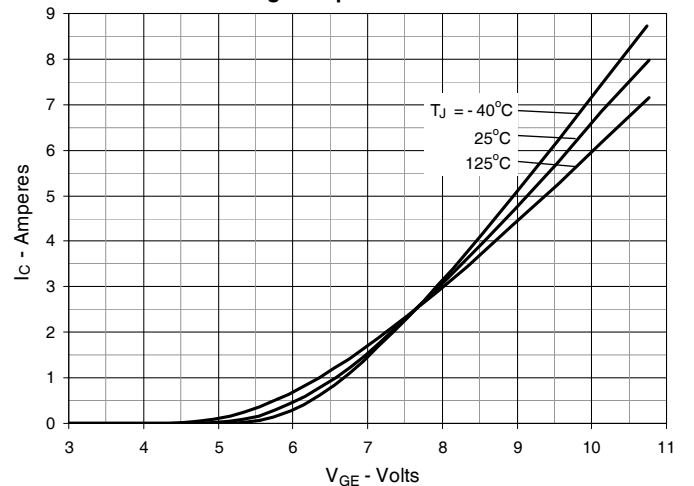


Fig. 7. Transconductance

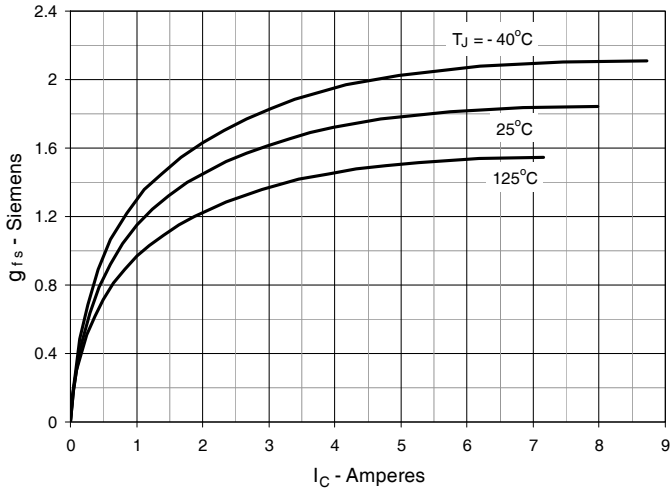


Fig. 8. Forward Voltage Drop of Intrinsic Diode

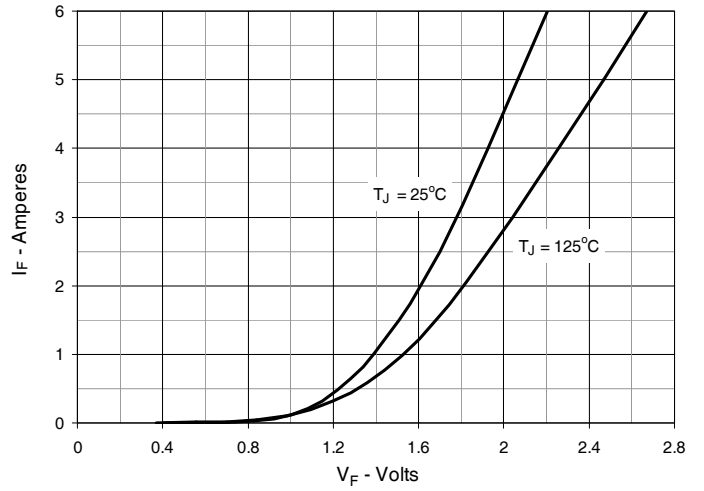


Fig. 9. Gate Charge

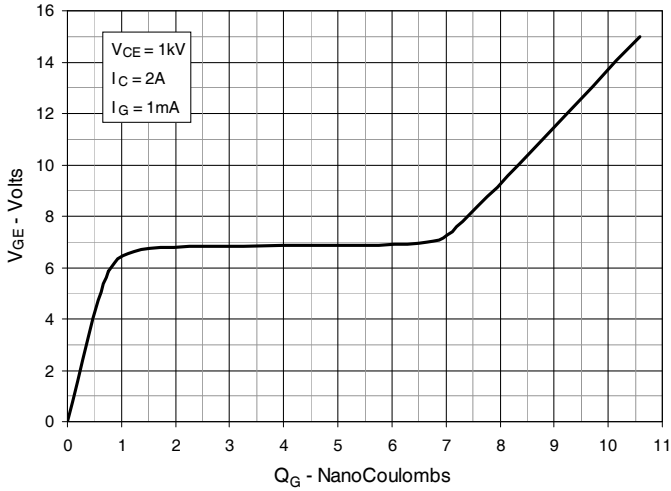


Fig. 10. Capacitance

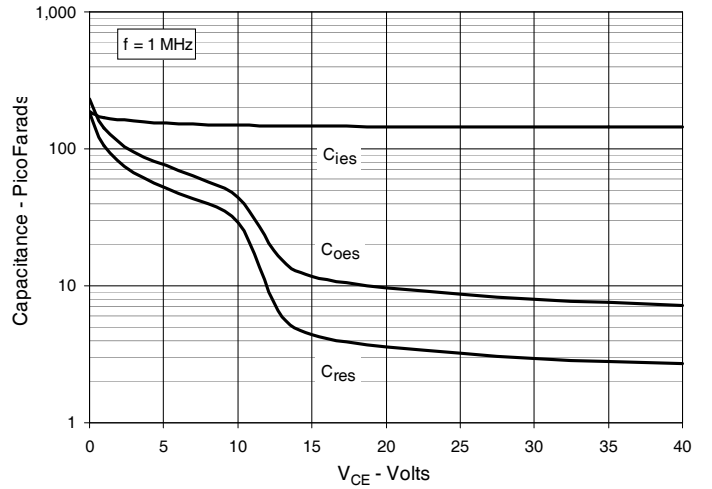


Fig. 11. Reverse-Bias Safe Operating Area

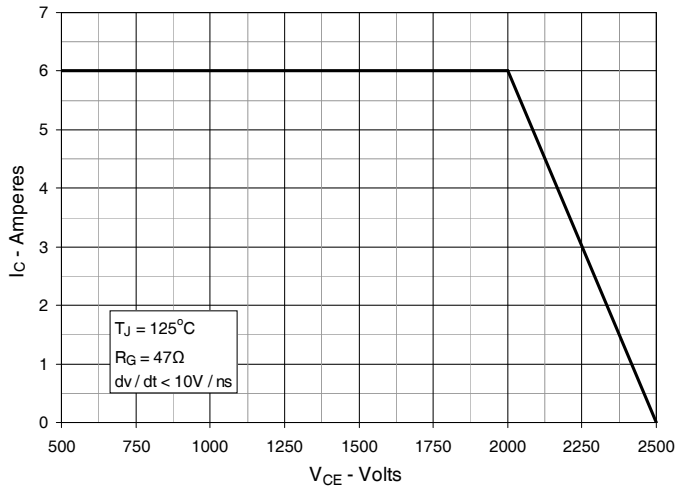
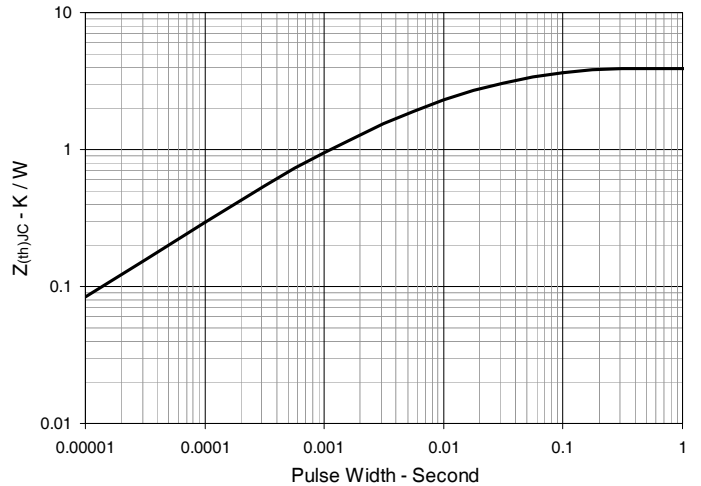
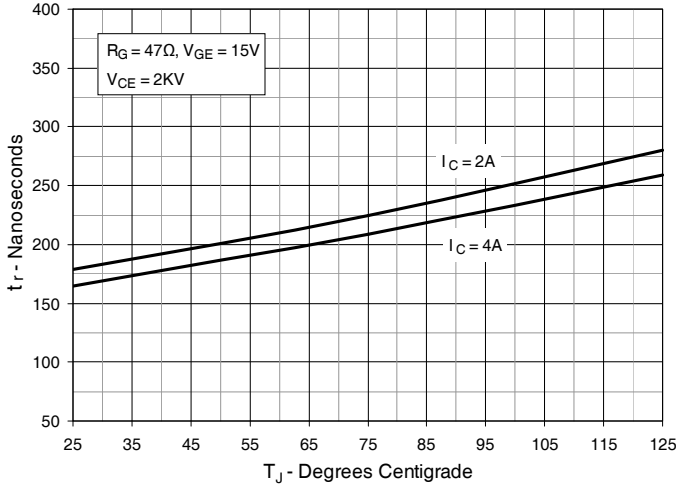


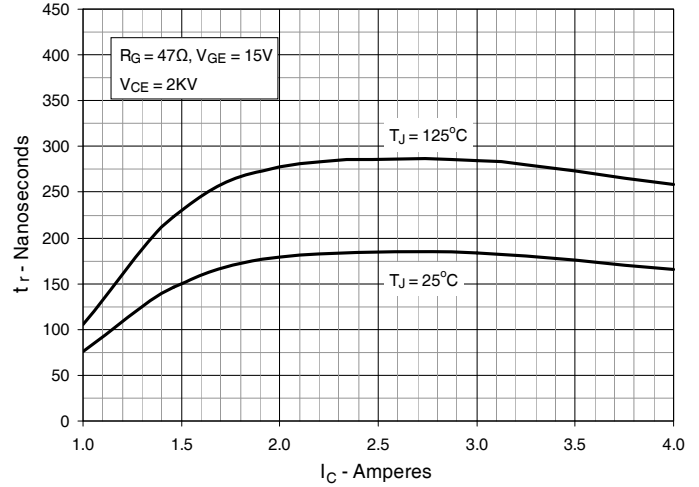
Fig. 12. Maximum Transient Thermal Impedance



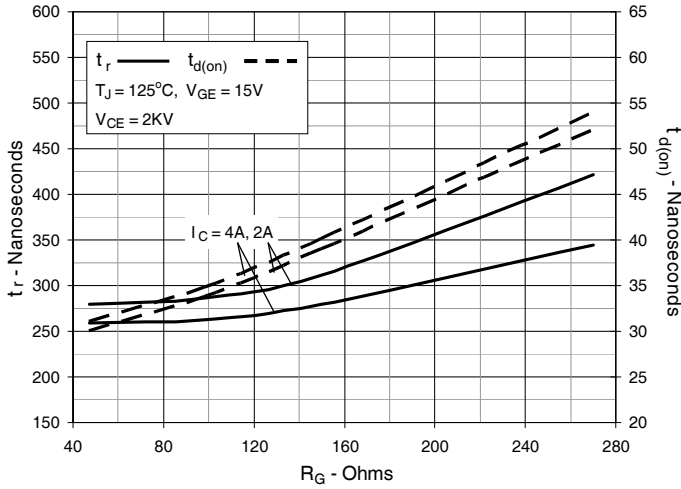
**Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature**



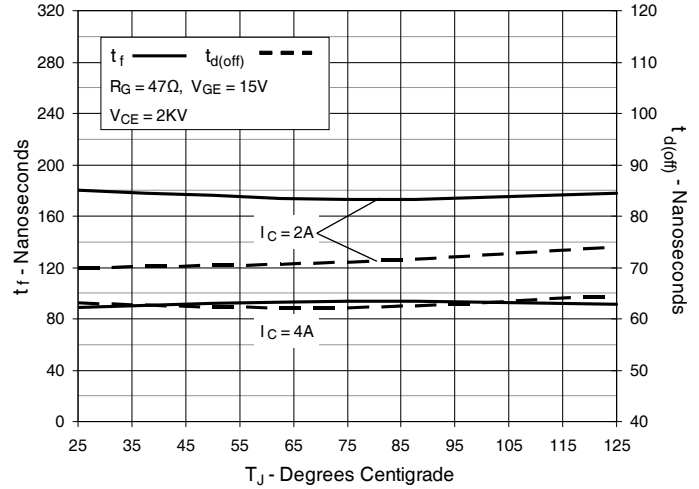
**Fig. 14. Resistive Turn-on Rise Time vs. Collector Current**



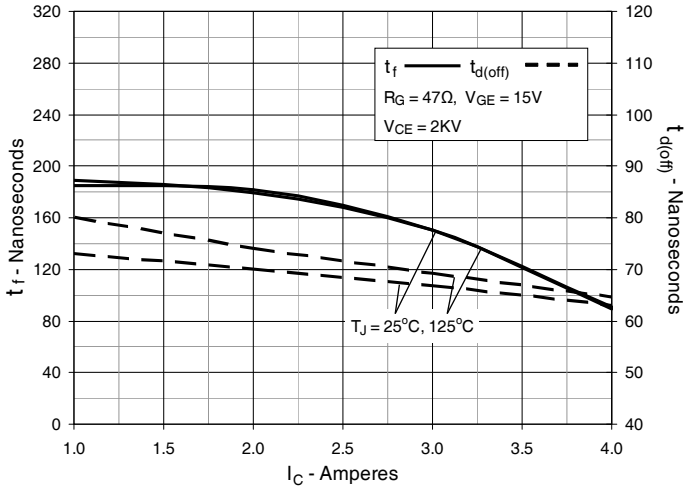
**Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance**



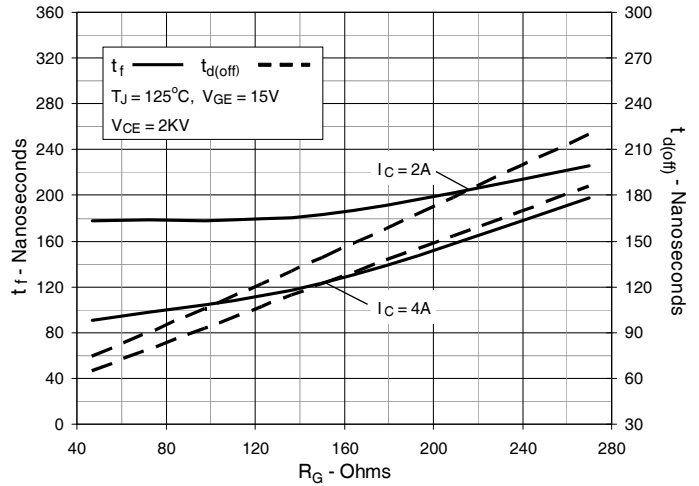
**Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature**



**Fig. 17. Resistive Turn-off Switching Times vs. Collector Current**



**Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance**





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